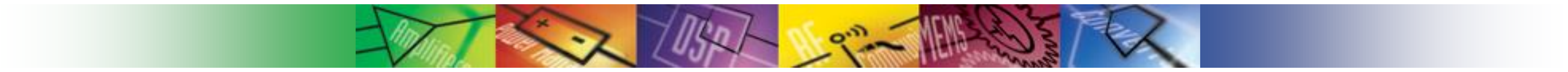

Product / Package Information

Package	LFCSP_SS
Body Size (mm)	4 X 4 X 1.45 (2.4 EP)
Lead Count	12
Terminal Finish	100 Sn
MS Number	MS011346B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.82E-02	93.70	937000	48.85	488535
Thermosets	Epoxy resin	Proprietary	9.04E-04	3.00	30000	1.56	15641
Thermosets	Phenol resin	Proprietary	9.04E-04	3.00	30000	1.56	15641
Other inorganic materials	Carbon black	1333-86-4	9.04E-05	0.30	3000	0.16	1564
Subtotal			3.01E-02	100.00	1000000	52.14	521382

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.62 E-02	96.20	962000	28.01	280096
Copper & its alloys	Nickel	7440-02-0	5.05 E-04	3.00	30000	0.87	8735
Copper & its alloys	Silicon	7440-21-3	1.09 E-04	0.65	6500	0.19	1893
Copper & its alloys	Magnesium	7439-95-4	2.52 E-05	0.15	1500	0.04	437
Subtotal			1.68 E-02	100.00	1000000	29.12	291160

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.81 E-04	100.0	1000000	0.31	3130

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.34 E-04	100.0	1000000	0.41	4050

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.84 E-04	99.0	990000	0.32	3190
Precious metals	Palladium	7440-05-3	1.86 E-06	1.00	10000	0.003	32
Subtotal			1.86 E-04	100.0	1000000	0.32	3222

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	7.01 E-03	100.0	1000000	12.13	121288

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Resin	Proprietary	1.60 E-03	50	500000	2.76	27616
Other organic materials	Ethene, tetrafluoro-,homopolymer	9002-84-0	1.44 E-03	45	450000	2.49	24854
Other organic materials	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	1.60 E-04	5	50000	0.28	2762
Subtotal			3.19 E-03	100.0	1000000	5.52	55231

Metal Seal

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Aluminum & its alloys	Aluminum	7429-90-5	1.55 E-05	50.00	500000	0.0269	269
Other inorganic materials	Germanium	7440-56-4	7.76 E-06	25.00	250000	0.0134	134
Aluminum & its alloys	Copper	7440-50-8	4.66 E-06	15.00	150000	0.0081	81
Other inorganic materials	Tungsten	7440-33-7	2.48 E-06	8.00	80000	0.0043	43
Other inorganic materials	Titanium	7440-32-6	6.21 E-07	2.00	20000	0.0011	11
Subtotal			3.10 E-05	100.00	1000000	0.05	537

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.78 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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